

查询"5962-89545012A"供应商

[illegible]

DESC FORM 193
SEP 87

* U.S. GOVERNMENT PRINTING OFFICE: 1987 — 748-129/60911
5962-E1197

DISTRIBUTION STATEMENT A. Approved for public release; distribution is unlimited.

1. SCOPE

1.1 Scope. This drawing describes device requirements for class B microcircuits in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices".

1.2 Part number. The complete part number shall be as shown in the following example:

5962-89545	01	R	X
Drawing number	Device type (1.2.1)	Case outline (1.2.2)	Lead finish per MIL-M-38510

1.2.1 Device type. The device type shall identify the circuit function as follows:

Device type	Generic number	Circuit function
01	54F579	8-bit bidirectional binary counter, with three-state outputs

1.2.2 Case outlines. The case outlines shall be as designated in appendix C of MIL-M-38510, and as follows:

Outline letter	Case outline
R	D-8 (20-lead, 1.060" x .310" x .200"), dual-in-line package
S	F-9 (20-lead, .540" x .300" x .100"), flat package
2	C-2 (20-terminal, .358" x .358" x .100"), square chip carrier package

1.3 Absolute maximum ratings.

Supply voltage range	- - - - -	-0.5 V dc minimum to +7.0 V dc maximum
Input voltage range	- - - - -	-0.5 V dc minimum to +7.0 V dc maximum
Input current range	- - - - -	-30 to +5.0 mA
Voltage applied to output in high output state	- -	-0.5 to +V _{CC}
Current applied to output in low output state	- -	40 mA
Storage temperature range	- - - - -	-65°C to +150°C
Maximum power dissipation (P _D) 1/	- - - - -	825 mW
Lead temperature (soldering, 10 seconds)	- - - - -	+300°C
Thermal resistance, junction-to-case (θ _{JC})	- - - - -	See MIL-M-38510, appendix C
Junction temperature (T _J)	- - - - -	+175°C

1.4 Recommended operating conditions.

Supply voltage (V _{CC})	- - - - -	4.5 V dc minimum to 5.5 V dc maximum
High level input voltage (V _{IH})	- - - - -	2.0 V
Low level input voltage (V _{IL})	- - - - -	0.8 V
Case temperature (T _C)	- - - - -	-55°C to +125°C

1/ Must withstand the added P_D due to short circuit test; e.g., I_{OS}.

STANDARDIZED MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A	5962-89545	
		REVISION LEVEL	SHEET 2

DESC FORM 193A
SEP 87

* U. S. GOVERNMENT PRINTING OFFICE: 1988-549-984

1.4 Recommended operating conditions - Continued. 2/

Minimum setup time, I/O _n to CP ($t_{S(H)}$, $t_{S(L)}$):	
$T_C = +25^\circ\text{C}$	3.0 ns
$T_C = -55^\circ\text{C}, +125^\circ\text{C}$	4.0 ns
Minimum hold time, I/O _n to CP ($t_{H(H)}$, $t_{H(L)}$):	
$T_C = +25^\circ\text{C}$	0.0 ns
$T_C = -55^\circ\text{C}, +125^\circ\text{C}$	0.0 ns
Minimum setup time, \overline{PE} , \overline{SR} , or \overline{CS} to CP, ($t_{S(H)}$):	
$T_C = +25^\circ\text{C}$	9.5 ns
$T_C = -55^\circ\text{C}, +125^\circ\text{C}$	11.0 ns
Minimum setup time, \overline{PE} , \overline{SR} , or \overline{CS} to CP, ($t_{S(L)}$):	
$T_C = +25^\circ\text{C}$	9.5 ns
$T_C = -55^\circ\text{C}, +125^\circ\text{C}$	13.0 ns
Minimum hold time, \overline{PE} , \overline{SR} or \overline{CS} to CP, ($t_{H(H)}$, $t_{H(L)}$):	
$T_C = +25^\circ\text{C}$	0.0 ns
$T_C = -55^\circ\text{C}, +125^\circ\text{C}$	0.0 ns
Minimum setup time, \overline{CEP} or \overline{CET} to CP, ($t_{S(H)}$):	
$T_C = +25^\circ\text{C}$	5.0 ns
$T_C = -55^\circ\text{C}, +125^\circ\text{C}$	7.5 ns
Minimum setup time, \overline{CEP} or \overline{CET} to CP, ($t_{S(L)}$):	
$T_C = +25^\circ\text{C}$	9.0 ns
$T_C = -55^\circ\text{C}, +125^\circ\text{C}$	11.5 ns
Minimum hold time \overline{CEP} or \overline{CET} to CP, ($t_{H(H)}$, $t_{H(L)}$):	
$T_C = +25^\circ\text{C}$	0.0 ns
$T_C = -55^\circ\text{C}, +125^\circ\text{C}$	0.0 ns
Minimum clock pulse width, ($t_{W(H)}$, $t_{W(L)}$):	
$T_C = +25^\circ\text{C}$	4.5 ns
$T_C = -55^\circ\text{C}, +125^\circ\text{C}$	6.0 ns
Minimum \overline{MR} pulse width ($t_{W(L)}$):	
$T_C = +25^\circ\text{C}$	3.0 ns
$T_C = -55^\circ\text{C}, +125^\circ\text{C}$	3.0 ns
Minimum recovery time (t_{REC}):	
$T_C = +25^\circ\text{C}$	4.0 ns
$T_C = -55^\circ\text{C}, +125^\circ\text{C}$	5.0 ns

2/ See figure 4, waveform 5.

STANDARDIZED MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A	5962-89545	
		REVISION LEVEL	SHEET 3

DESC FORM 193A
SEP 87

☆ U. S. GOVERNMENT PRINTING OFFICE: 1986-549-904

2. APPLICABLE DOCUMENTS

2.1 Government specification and standard. Unless otherwise specified, the following specifications and standard, of the issue listed in that issue of the Department of Defense Index of Specifications and Standards specified in the solicitation, form a part of this drawing to the extent specified herein.

SPECIFICATION

MILITARY

MIL-M-38510 - Microcircuits, General Specification for.

STANDARD

MILITARY

MIL-STD-883 - Test Methods and Procedures for Microelectronics.

(Copies of the specification and standard required by manufacturers in connection with specific acquisition functions should be obtained from the contracting activity or as directed by the contracting activity.)

2.2 Order of precedence. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing shall take precedence.

3. REQUIREMENTS

3.1 Item requirements. The individual item requirements shall be in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices" and as specified herein.

3.2 Design, construction, and physical dimensions. The design, construction, and physical dimensions shall be as specified in MIL-M-38510 and herein.

3.2.1 Terminal connections. The terminal connections shall be as specified on figure 1.

3.2.2 Truth table. The truth table shall be as specified on figure 2.

3.2.3 Logic diagram. The logic diagram shall be as specified on figure 3.

3.2.4 Test circuit and switching waveforms. The test circuit and switching waveforms shall be as specified on figure 4.

3.2.5 Case outline. The case outline shall be in accordance with 1.2.2 herein.

3.3 Electrical performance characteristics. Unless otherwise specified, the electrical performance characteristics are as specified in table I and apply over the full case operating temperature range.

3.4 Marking. Marking shall be in accordance with MIL-STD-883 (see 3.1 herein). The part shall be marked with the part number listed in 1.2 herein. In addition, the manufacturer's part number may also be marked as listed in 6.4 herein.

3.5 Certificate of compliance. A certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in 6.4. The certificate of compliance submitted to DESC-ECS prior to listing as an approved source of supply shall state that the manufacturer's product meets the requirements of MIL-STD-883 (see 3.1 herein) and the requirements herein.

STANDARDIZED MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A		5962-89545
		REVISION LEVEL	SHEET 4

DESC FORM 193A
SEP 87

★ U. S. GOVERNMENT PRINTING OFFICE: 1988-549-904

TABLE I. Electrical performance characteristics.

Test	Symbol	Conditions -55°C < T _C < +125°C unless otherwise specified		Group A subgroups	Limits		Unit
					Min	Max	
High level output voltage T _C	V _{OH1}	V _{CC} = 4.5 V, V _{IL} = 0.8 V V _{IH} = 2.0 V, I _{OH} = -1.0 mA		1, 2, 3	2.5		V
High level output voltage, I/O _n	V _{OH2}	V _{CC} = 4.5 V V _{IH} = 2.0 V V _{IL} = 0.8 V	I _{OH} = -3.0	1, 2, 3	2.4		V
			I _{OH} = -1.0	1, 2, 3	2.5		V
Low level output voltage	V _{OL}	V _{CC} = 4.5 V I _{OL} = 20 mA V _{IL} = 0.8 V, V _{IH} = 2.0 V		1, 2, 3		0.50	V
Input clamp voltage	V _{IK}	V _{CC} = 4.5 V, I _{IN} = -18 mA		1, 2, 3		-1.2	V
Input current at maximum input voltage	I _{IH1}	V _{CC} = 5.5 V V _{IN} = 5.5 V	I/O _n	1, 2, 3		1.0	mA
		V _{CC} = 5.5 V V _{IN} = 7.0 V	all others	1, 2, 3		100	μA
High level input current, except I/O _n	I _{IH2}	V _{CC} = 5.5 V, V _{IN} = 2.7 V		1, 2, 3		20	μA
Low level input current, except I/O _n	I _{IL1}	V _{CC} = 5.5 V, V _{IN} = 0.5 V		1, 2, 3		0.6	mA
Off state current high level voltage applied to I/O _n	I _{OZH}	V _{CC} = 5.5 V, V _{IN} = 2.7 V, V _{IH} = 2.0 V		1, 2, 3		70	μA
Off state current low level voltage applied to I/O _n	I _{OZL}	V _{CC} = 5.5 V, V _{IN} = 0.5 V, V _{IH} = 2.0 V		1, 2, 3		-600	μA
Short circuit output current	I _{OS}	V _{CC} = 5.5 V, V _{OUT} = GND 1/		1, 2, 3	-60	-150	mA

See footnotes at end of table.

STANDARDIZED MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A		5962-89545
		REVISION LEVEL	SHEET 5

DESC FORM 193A
SEP 87

★ U. S. GOVERNMENT PRINTING OFFICE: 1988-549-904

TABLE I. Electrical performance characteristics - Continued.								
Test	Symbol	Conditions -55°C < T _C < +125°C unless otherwise specified		Group A subgroups	Limits		Unit	
					Min	Max		
Supply current (total)	I _{CCH}	V _{CC} = 5.5 V		1, 2, 3		135	mA	
	I _{CCL}			1, 2, 3		145	mA	
	I _{CCZ}			1, 2, 3		150	mA	
Functional tests		See 4.3.1c		7, 8				
Maximum clock frequency	f _{MAX}	See waveform 1 2/		9 10,11	100 80		MHz	
Propagation delay CP to I/O _n	t _{PLH1}	V _{CC} = 5.0 V C _L = 50 pF R _L = 500Ω See figure 4	See waveform 1	9 10,11	5.0 4.5	10.5 23.0	ns	
	t _{PHL1}			9 10,11	5.0 5.0	10.5 12.5	ns	
Propagation delay CP to TC	t _{PLH2}		See waveform 1	9 10,11	5.5 5.0	10.0 19.5	ns	
	t _{PHL2}			9 10,11	5.5 5.0	10.0 12.0	ns	
Propagation delay U/D to TC	t _{PLH3}		See waveform 4	9 10,11	3.5 3.5	8.0 12.5	ns	
	t _{PHL3}			9 10,11	4.5 4.5	8.0 10.0	ns	
Propagation delay CET to TC	t _{PLH4}		See waveform 3	9 10, 11	3.5 3.5	7.0 9.5	ns	
	t _{PHL4}			9 10,11	3.5 3.5	8.0 9.0	ns	
Propagation delay MR to I/O _n	t _{PHL5}		See waveform 2	9 10,11	5.0 5.0	9.0 11.0	ns	
See footnotes at end of table								
STANDARDIZED MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444			SIZE A	5962-89545		SHEET 6		
			REVISION LEVEL					

DESC FORM 193A
SEP 87

★ U. S. GOVERNMENT PRINTING OFFICE: 1988-549-904

TABLE I. Electrical performance characteristics - Continued.

Test	Symbol	Conditions -55°C < T _C < +125°C unless otherwise specified	Group A subgroups	Limits		Unit	
				Min	Max		
Output disable time from high to low level CS, PE, to I/O _n	tpHZ1	VCC = 5.0 V CL = 50 pF RL = 500Ω See figure 4	See waveform 6	9 10,11	3.0 3.0	7.5 10.0	ns
	tpLZ1		See waveform 7	9 10,11	6.5 5.5	9.5 12.0	ns
Output enable time to high or low level CS, PE, to I/O _n	tpZH2		See waveform 6	9 10,11	5.0 3.5	10.5 12.5	ns
	tpZL2		See waveform 7	10,11 10,11	6.5 5.5	10.5 13.0	ns
Output disable time from high to low level OE to I/O _n	tpHZ3		See waveform 6	9 10,11	1.0 1.0	4.0 8.0	ns
	tpLZ3		See waveform 7	9 10,11	2.5 2.0	7.0 10.0	ns
Output enable time to high or low level OE to I/O _n	tpZH4		See waveform 6	9 10,11	4.0 3.5	8.5 11.0	ns
	tpZL4		See waveform 7	9 10,11	5.0 4.5	9.5 11.5	ns

1/ Not more than one output should be shorted at a time. For testing I_{OS}, the use of high-speed test apparatus, sample-and-hold techniques, or both are preferable in order to minimize internal heating and more accurately reflect operational values. Otherwise, prolonged shorting of a high output may raise the chip temperature well above normal and thereby cause invalid readings in other parameter tests. In any sequence of parameter tests, I_{OS} tests should be performed last.

2/ This parameter is guaranteed but not tested to the specified limits in table I.

3.6 Certificate of conformance. A certificate of conformance as required in MIL-STD-883 (see 3.1 herein) shall be provided with each lot of microcircuits delivered to this drawing.

3.7 Notification of change. Notification of change to DESC-ECS shall be required in accordance with MIL-STD-883 (see 3.1 herein).

3.8 Verification and review. DESC, DESC's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.

STANDARDIZED MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A		5962-89545
		REVISION LEVEL	SHEET 7

DESC FORM 193A
SEP 87

☆ U. S. GOVERNMENT PRINTING OFFICE: 1988-549-904

Case outlines	R and S	2
Terminal number	Terminal symbol	
1	CP	CET
2	I/O ₀	CEP
3	I/O ₁	SR
4	I/O ₂	MR
5	I/O ₃	CP
6	GND	I/O ₀
7	I/O ₄	I/O ₁
8	I/O ₅	I/O ₂
9	I/O ₆	I/O ₃
10	I/O ₇	GND

Case outlines	R and S	2
Terminal number	Terminal symbol	
11	OE	I/O ₄
12	CS	I/O ₅
13	PE	I/O ₆
14	U/D	I/O ₇
15	TC	OE
16	VCC	CS
17	CET	PE
18	CEP	U/D
19	SR	TC
20	MR	VCC

FIGURE 1. Terminal connections.

STANDARDIZED MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A	5962-89545	
		REVISION LEVEL	SHEET 8

DESC FORM 193A
SEP 87

☆ U. S. GOVERNMENT PRINTING OFFICE: 1988-550-547

Inputs								Operating mode	
MR	SR	CS	PE	CEP	CET	U/D	OE	CP	
X	X	H	X	X	X	X	X	X	I/O to I/O ₇ in high impedance (\overline{PE} disabled)
X	X	L	H	X	X	X	H	X	I/O to I/O ₇ in high impedance
X	X	L	H	X	X	X	L	X	Flip-flop output appears on I/O lines
L	X	X	X	X	X	X	X	X	Asynchronous reset for all flip-flops
H	L	X	X	X	X	X	X	↑	Synchronous reset for all flip-flops
H	H	L	L	X	X	X	X	↑	Parallel load all flip-flops
H	H	(not LL)	H	X	X	X	X	↑	Hold
H	H	(not LL)	X	H	H	X	X	↑	Hold (\overline{TC} held High)
H	H	(not LL)	L	L	L	H	X	↑	Count up
H	H	(not LL)	L	L	L	L	X	↑	Count down

H = High voltage level
L = Low voltage level
X = Irrelevant
↑ = Low to High clock transition

(not LL) = \overline{CS} and \overline{PE} should never be low voltage level at the same time.

FIGURE 2. Truth table.

STANDARDIZED MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A	5962-89545	
	REVISION LEVEL		SHEET 9

DESC FORM 193A
SEP 87

★ U. S. GOVERNMENT PRINTING OFFICE: 1988-550-547

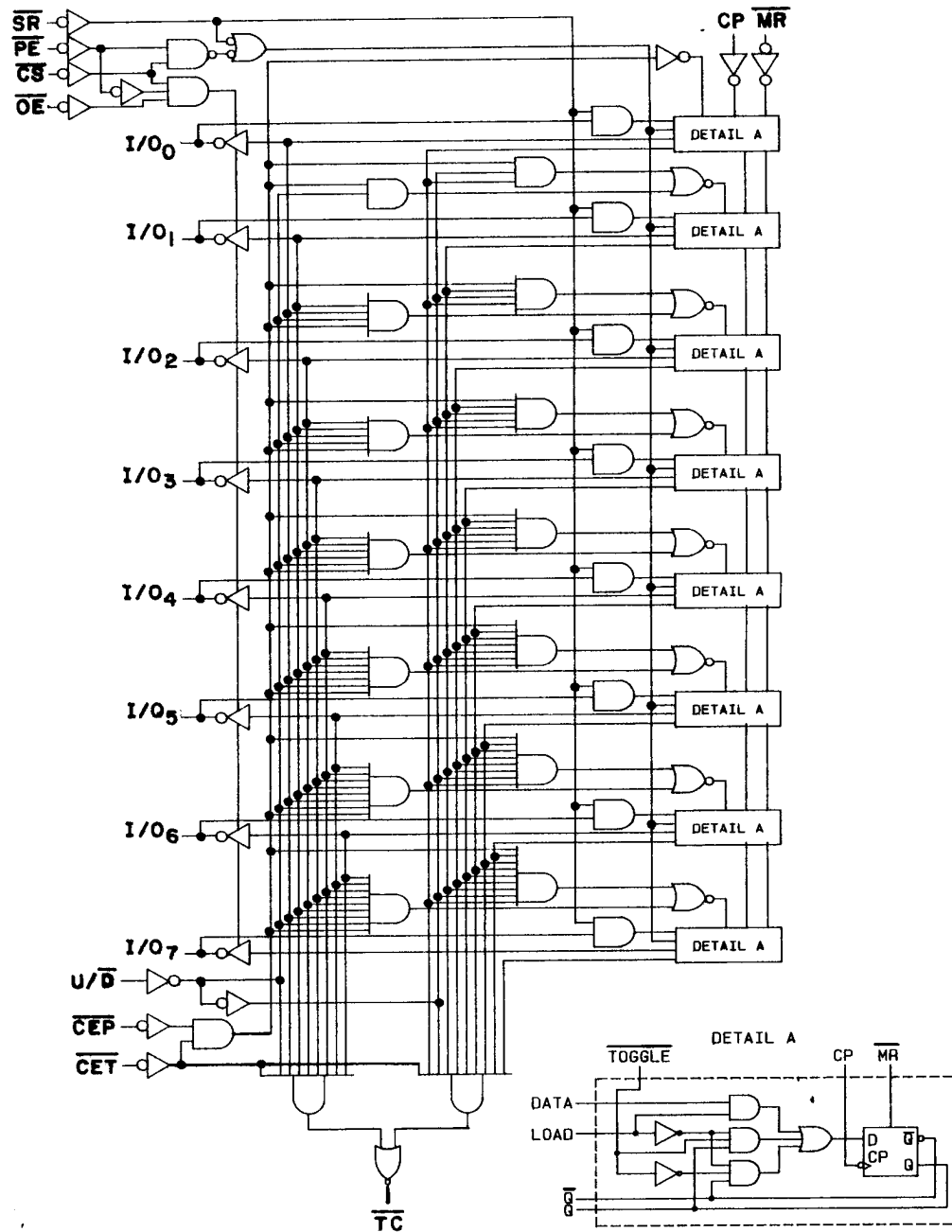
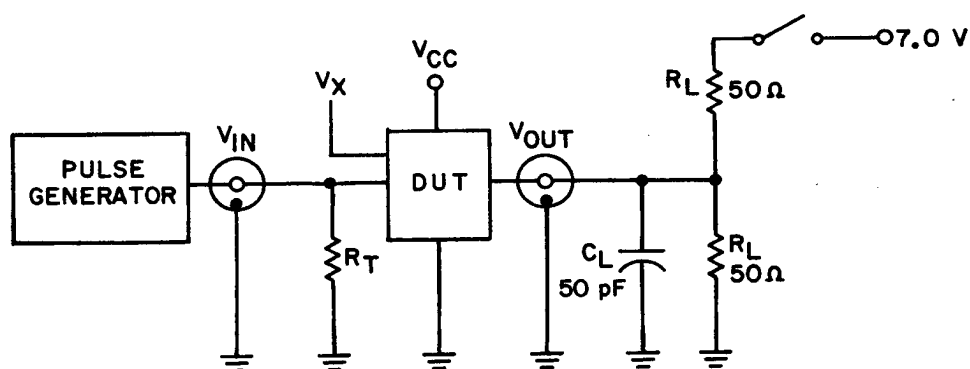


FIGURE 3. Logic diagram.

STANDARDIZED MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A		5962-89545
		REVISION LEVEL	SHEET 10

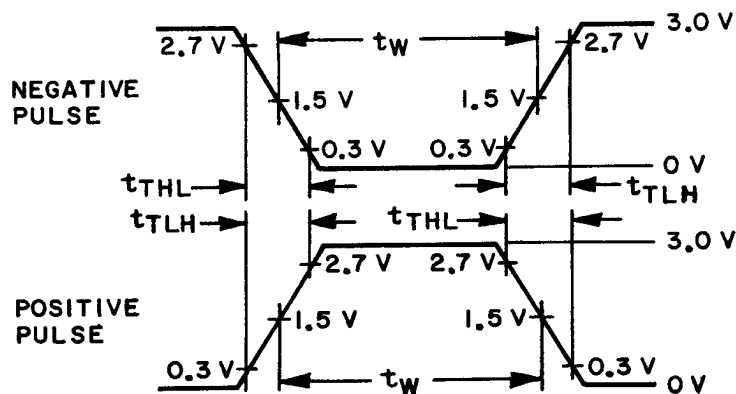
DESC FORM 193A
SEP 87

* U. S. GOVERNMENT PRINTING OFFICE: 1988-549-904



Switch position

Test	Switch
t_{PLZ}	Closed
t_{PZL}	Closed
All other	Open



NOTES:

- Input pulse characteristics: $PRR = 1 \text{ MHz}$, $t_W = 500 \text{ ns}$, $t_{TLH} = t_{THL} \leq 2.5 \text{ ns}$, duty cycle = 50 percent.
- R_T = Termination resistance should be equal to Z_{OUT} of pulse generator.
- V_X = Unclocked pins must be held at $\leq 0.8 \text{ V}$, $\geq 2.7 \text{ V}$ or open.

FIGURE 4. Test circuit and switching waveforms.

STANDARDIZED MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A		5962-89545
		REVISION LEVEL	SHEET 11

DESC FORM 193A
SEP 87

U. S. GOVERNMENT PRINTING OFFICE: 1988-550-547

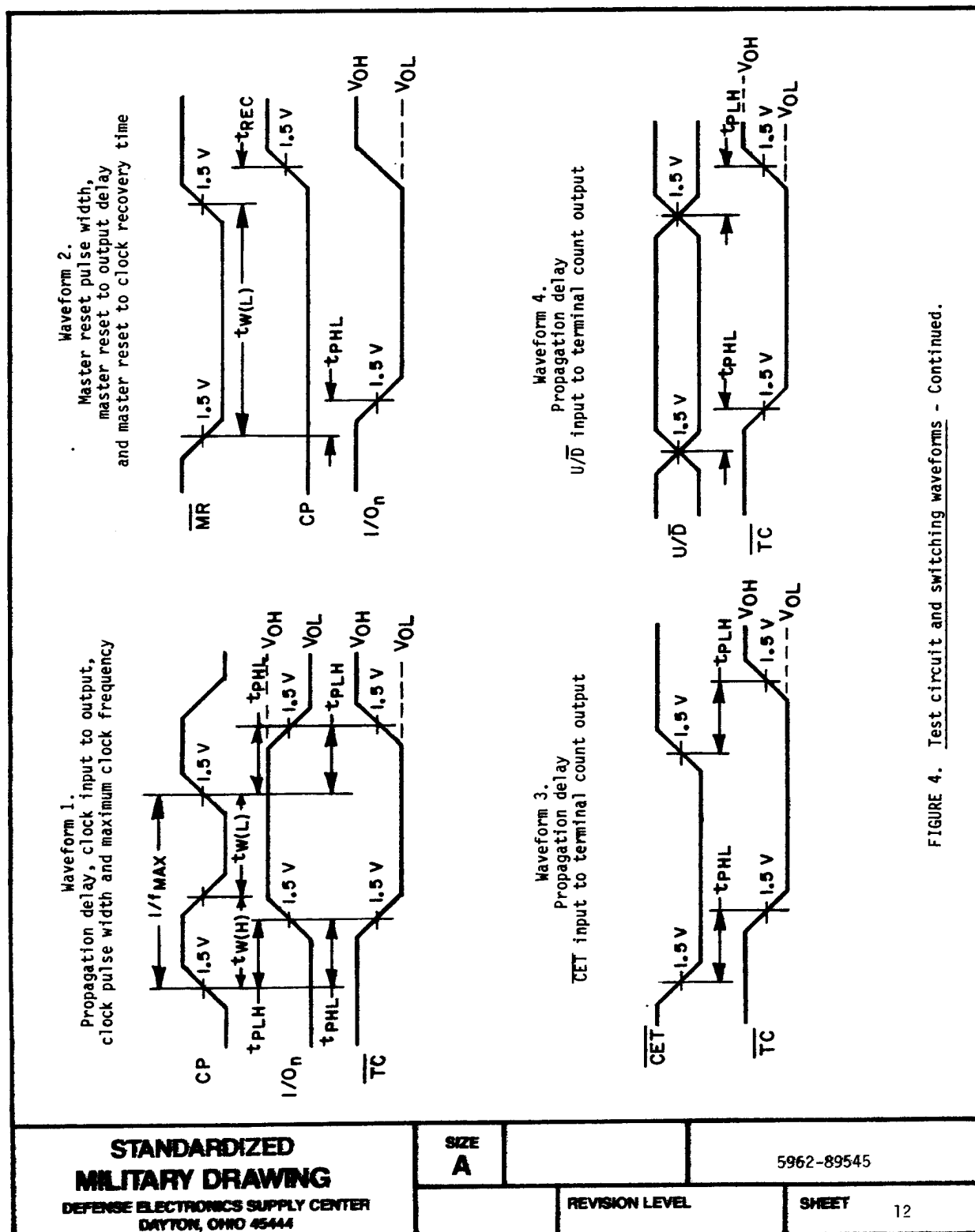
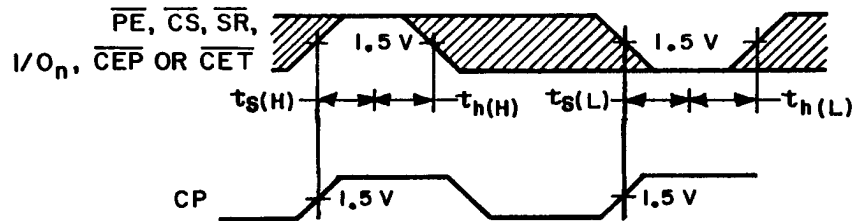
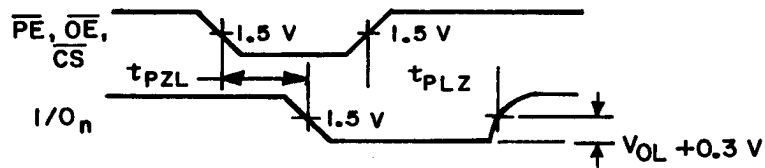


FIGURE 4. Test circuit and switching waveforms - Continued.

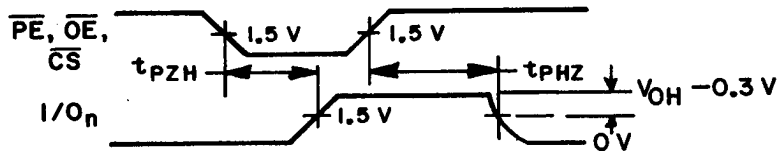
Waveform 5.
Data setup and hold times



Waveform 6.
Three-state output enable time to high level
and output disable time from high level



Waveform 7.
Three-state output enable time to low level
and output disable time from low level



NOTE: The shaded areas indicate when the input is permitted to change for predictable output performance.

FIGURE 4. Test circuit and switching waveforms - Continued.

STANDARDIZED MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A		5962-89545
		REVISION LEVEL	SHEET 13

DESC FORM 193A
SEP 87

★ U. S. GOVERNMENT PRINTING OFFICE: 1968-550-547

4. QUALITY ASSURANCE PROVISIONS

4.1 Sampling and inspection. Sampling and inspection procedures shall be in accordance with section 4 of MIL-M-38510 to the extent specified in MIL-STD-883 (see 3.1 herein).

4.2 Screening. Screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection. The following additional criteria shall apply:

- a. Burn-in test, method 1015 of MIL-STD-883.
 - (1) Test condition A, B, C, or D using the circuit submitted with the certificate of compliance (see 3.5 herein).
 - (2) $T_A = +125^{\circ}\text{C}$, minimum.
- b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.

4.3 Quality conformance inspection. Quality conformance inspection shall be in accordance with method 5005 of MIL-STD-883 including groups A, B, C, and D inspections. The following additional criteria shall apply.

4.3.1 Group A inspection.

- a. Tests shall be as specified in table II herein.
- b. Subgroups 4, 5, and 6 in table I, method 5005 of MIL-STD-883 shall be omitted.
- c. Subgroup 7 and 8 tests shall verify the truth table as specified on figure 2.

4.3.2 Groups C and D inspections.

- a. End-point electrical parameters shall be as specified in table II herein.
- b. Steady-state life test conditions, method 1005 of MIL-STD-883:
 - (1) Test condition A, B, C, or D using the circuit submitted with the certificate of compliance (see 3.5 herein).
 - (2) $T_A = +125^{\circ}\text{C}$, minimum.
 - (3) Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883

STANDARDIZED MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A		5962-89545
		REVISION LEVEL	SHEET 14

DESC FORM 193A
SEP 87

* U. S. GOVERNMENT PRINTING OFFICE: 1986-545-904

TABLE II. Electrical test requirements.

MIL-STD-883 test requirements	Subgroups (per method 5005, table I)
Interim electrical parameters (method 5004)	---
Final electrical test parameters (method 5004)	1*,2,3,7,8,9, 10,11
Group A test requirements (method 5005)	1,2,3,7,8, 9,10,11
Group C and D end-point electrical parameters (method 5005)	1,2,3

* PDA applies to subgroup 1.

5. PACKAGING

5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-M-38510.

6. NOTES

6.1 Intended use. Microcircuits conforming to this drawing are intended for use when military specifications do not exist and qualified military devices that will perform the required function are not available for OEM application. When a military specification exists and the product covered by this drawing has been qualified for listing on QPL-38510, the device specified herein will be inactivated and will not be used for new design. The QPL-38510 product shall be the preferred item for all applications.

6.2 Replaceability. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.

6.3 Comments. Comments on this drawing should be directed to DESC-ECS, Dayton, Ohio 45444, or telephone 513-296-5375.

STANDARDIZED MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A		5962-89545
		REVISION LEVEL	SHEET 15

DESC FORM 193A
SEP 87

★ U. S. GOVERNMENT PRINTING OFFICE: 1968-549-904

6.4 Approved source of supply. An approved source of supply is listed herein. Additional sources will be added as they become available. The vendor listed herein has agreed to this drawing and a certificate of compliance (see 3.5 herein) has been submitted to DESC-ECs.

Military drawing part number	Vendor CAGE number	Vendor similar part number 1/
5962-8954501RX	18324	54F579/BRA
5962-8954501SX	18324	54F579/BSA
5962-89545012X	18324	54F579/B2A

1/ Caution. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.

Vendor CAGE number

18324

Vendor name and address

Signetics Corporation
4130 South Market Court
Sacramento, CA 95834

STANDARDIZED MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A		5962-89545
		REVISION LEVEL	SHEET 16

DESC FORM 193A
SEP 87

* U. S. GOVERNMENT PRINTING OFFICE: 1988-548-904

010990 ✓ _ _ _